PCN 15_0156 ADG836 Wafer Fabrication Change from TSMC Fab 7A to TSMC Fab 11

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC *JESD22-A108*	**2x45** **7x77**	**Pass**
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**4x77** **5x45**	**Pass**
ELF	MIL-STD-883, *Method 1015*	**3x667** **3x667** **3x667**	**Pass**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1x77** **3x45**	**Pass**
Latch-Up	JEDEC *JESD78*	**3**	**Pass**
Electrostatic Discharge *Human Body Model*	ESDA/JEDEC *JS-001*	**3/voltage**	**Pass_4000V**
Electrostatic Discharge *Machine Model*	JEDEC *JESD22*-A115	**3/voltage**	**Pass _200V**
Electrostatic Discharge *Field-Induced Charged Device Model*	JEDEC *JESD22-C101*	**3/voltage**	**Pass _1250V**

*Preconditioned per JEDEC/IPC J-STD-020